

PFR-010 Title: Grounding of SMA Circuit on SPB

Assembly: SPB Release Mechanism		SubAssembly: S	SubAssembly: SMA Circuit	
Component: Si	MA Attach Block			
Originator: B. Donakowski/ 13 Jan 05		Organization: UCB/SSL/EFI		
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Failure Occurred ◆ Functional test	During (Check one √) ☐ Qualification test	□ S/C Integration	☐ Launch operations	
Environment who	en failure occurred:			
♦ Ambient	☐ Vibration	□ Shock	□ Acoustic	
☐ Thermal	□ Vacuum	☐ Thermal-Vacuum	□ EMI/EMC	
	Problem	Description		
During CPT testing, the open the SPB Release	n, we would like to know as me SMA circuit was found to labors. Inspection revealed as touching the structure Front	be grounded to chassis. To a screw head on the SMA		
Analyses Performed to Determine Cause				
Inspection of hardwar clearance approximate	w the failure happened? Was it e and design on SolidWorks rely .005". Any misalignment Note this problem has occurre	eveals screw head is very or mis-machining of part	close to Front Panel, nominal	
Corrective Action/ Resolution				
Screw is used to hold Assy build-up. Once and therefore the clam	it? And how do we make sure a clamp block down which is the Release Ring Assy is insta up plate and screw is not perfo emove Screw and Clamp Plate	required to keep SMA with alled into the SPB, the SM orming any function.	re constrained during Sub-	
Acceptance: MAM: Ron Jackson; MSE: Ellen Taylor				
Date of Closure				



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